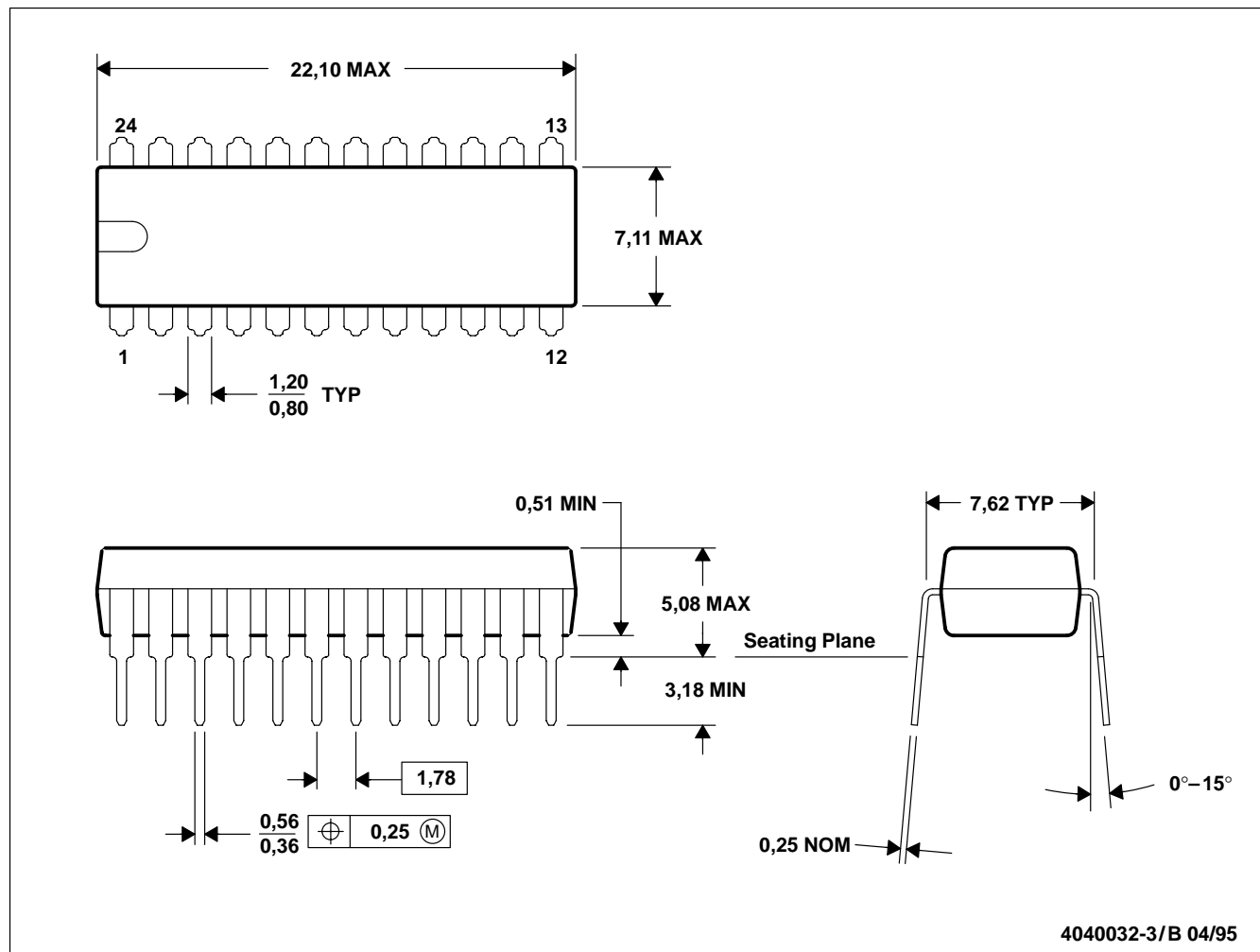


NN (R-PDIP-T24)

PLASTIC SHRINK DUAL-IN-LINE PACKAGE



- NOTES: A. All linear dimensions are in millimeters.
 B. This drawing is subject to change without notice.
 C. Body dimensions include mold flash or protrusion.



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